



401 River Oaks Parkway, San Jose, California 95134 (408) 577-6200

28-PIN QFN LEADFREE PACKAGE MATERIAL COMPOSITION

Applicable to: AH202-F, FP31QF-F, CVxxx-AF and VG101-F and VG111-F

	MATERIAL COMPONENT	MATERIAL	CAS #	WEIGHT (mg)	ppm
1	28-PIN QFN Leadframe Bulk	Copper	7440-50-8	45	431994
2	28-PIN QFN Leadframe Bulk	Iron	7439-89-6	1.021	9801
3	28-PIN QFN Leadframe Bulk	Phosphorus	7723-14-0	0.65	6240
4	28-PIN QFN Leadframe Bulk	Zinc	7440-66-6	0.3	2880
5	QFN Matte Tin Finish Plating	Tin	7440-31-5	1.5	14400
6	Die Attach Epoxy & Paddle Plating	Silver	7440-22-4	0.5	4800
7	Die Attach Epoxy	Epoxy Resin	9003-36-5	0.04	384
8	Die Attach Epoxy	t-Butyl Phenyl Glycidyl Ether	3101-60-8	0.03	288
9	Die Attach Epoxy	Butyl Cellosolve Acetate	112-07-2	0.003	29
10	Die Attach Epoxy	Phenolic Hardner	92-88-6	0.005	48
11	Wirebond And Die Metallization	Gold	7440-57-5	0.3	2880
12	QFN Package Molding Compound	Antimony	7440-36-0	0.08	768
13	QFN Package Molding Compound	Bromide	24959-67-9	0.25	2400
14	QFN Package Molding Compound	Silica	7631-86-9	46	441594
15	QFN Package Molding Compound	Epoxy, Cresol Novolac		4	38400
16	QFN Package Molding Compound	Phenol Novolac		3	28800
17	QFN Package Molding Compound	Carbon	7440-44-0	0.2	1920
18	Active Semiconductor Die	Arsenic*	7440-38-2	0.634	6086
19	Active Semiconductor Die	Gallium*	7440-55-3	0.655	6288

Total: 104.2 1,000,000

* Individual amounts vary slightly based on minor differences to die size.

For questions, please contact Tad Custer, WJ Product Line Manager at 408-577-6370, or Tad.Custer@wj.com



401 River Oaks Parkway
San Jose, CA 95134

SIZE

DWG. NO.

454704

SCALE

REV.

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SHEET

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